



64MB/128MB REGISTERED SDRAM & 128MB SDRAM PBGA MCP
Quality and Reliability Report

**64MB/128MB REGISTERED SDRAM & 128MB SDRAM
PBGA MULTI-CHIP PACKAGE CONSTRUCTION**

APPLIES TO FOLLOWING PARTS

- WEDPN16N64V-XBX
- WEDPN16N72V-XBX
- WEDPN16N64VR-XBX
- WEDPN16N72VR-XBX
- WEDPN8N64VR-XBX
- WEDPN8N72VR-XBX

ORGANIZATIONS

- 16M x 64 SDRAM
- 16M x 72 SDRAM
- 16M x 64 Registered SDRAM
- 16M x 72 Registered SDRAM
- 8M x 64 Registered SDRAM
- 8M x 72 Registered SDRAM

ENCAPSULANT

- Thickness around die = 0.015 to 0.020 typical
- The encapsulant is not injection molded to control wire sweep effects
- T_G = 150°C
- Moisture sensitivity is to JEDEC level 3

INTERPOSER MATERIAL

- CTE = 12-13 ppm / °C
- Water absorption = 0.13%

BALLS

- Eutectic solder Sn63/Pb37
- Diameter = 0.835mm (0.032) Typical

TEST

- Burn-In - 100%-48 hours at 125°C
- Final Electrical Test - 100% at maximum and minimum ambient temperatures

Temperature Ranges Available:

- 55°C to +125°C
- 40°C to +85°C
- 0°C to +70°C

SHIPPING

- Final bake out
- Shipped in JEDEC standard trays and anti-static shielded dry pack bags
- Humidity indicator cards are included
- Desiccant used in dry packs

Qualification Information

Qual for 219 PBGA Product

Qual Test	# of Pieces	Duration	Reference Standards	Temp. Range	Results
Preconditioning	All Test Sample		EIA/JESD22 Method A113 (level3)		Passed
Bias Life Test	15	184 hrs	EIA/JESD22 Method A108	150°C	15 Passed
Temperature Cycle	15	1,000 cycles	EIA/JESD22 Method A104 Condition C	-65°C to +150°C	15 Passed
85/85 Bias	15	1,000 hrs	EIA/JESD22 Method 101	85°C	15 Passed

(Per Reliability Report)
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